

## GL Silicon N-Channel Power MOSFET

### General Description :

The CS540A4 uses advanced trench technology and design to provide excellent RDS(ON) with low gate charge. It can be used in a wide variety of applications. The package form is TO-252, which accords with the RoHS standard.

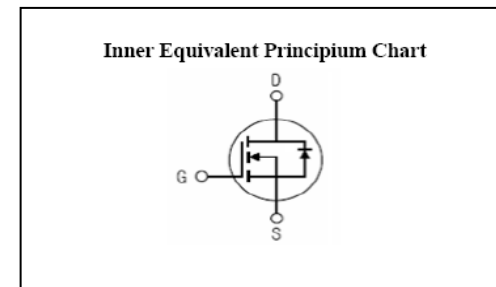
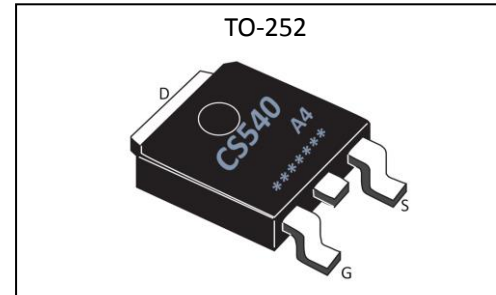
### Features :

- Fast Switching
- Low Gate Charge and Rds(on)
- Low Reverse transfer capacitances
- 100% Single Pulse avalanche energy Test

### Applications :

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

|                         |     |    |
|-------------------------|-----|----|
| V <sub>DSS</sub>        | 100 | V  |
| I <sub>D</sub>          | 30  | A  |
| P <sub>D</sub>          | 85  | W  |
| R <sub>DS(ON)type</sub> | 20  | mΩ |



### Absolute ( T<sub>c</sub>= 25°C unless otherwise specified ) :

| Symbol                            | Parameter  | Rating           | Units |
|-----------------------------------|--|------------------|-------|
| V <sub>DSS</sub>                  | Drain-to-Source Voltage                          | 100              | V     |
| I <sub>D</sub>                    | Continuous Drain Current                         | 30               | A     |
|                                   | Continuous Drain Current T <sub>c</sub> = 100 °C | 21               | A     |
| I <sub>DM</sub>                   | Pulsed Drain Current                             | 120              | A     |
| V <sub>GS</sub>                   | Gate-to-Source Voltage                           | ±20              | V     |
| E <sub>AS</sub> <sup>a2</sup>     | Single Pulse Avalanche Energy                    | 260              | mJ    |
| E <sub>AR</sub> <sup>a1</sup>     | Avalanche Energy ,Repetitive                     | 35               | mJ    |
| I <sub>AR</sub> <sup>a1</sup>     | Avalanche Current                                | 8                | A     |
| dv/dt <sup>a3</sup>               | Peak Diode Recovery dv/dt                        | 5.0              | V/ns  |
| P <sub>D</sub>                    | Power Dissipation                                | 85               | W     |
| T <sub>J</sub> , T <sub>stg</sub> | Operating Junction and Storage Temperature Range | 175 , -55 to 175 | °C    |
| T <sub>L</sub>                    | Maximum Temperature for Soldering                | 300              | °C    |



## GL Silicon N-Channel Power MOSFET

Electrical Characteristics ( Tc= 25°C unless otherwise specified ) :

| OFF Characteristics                 |                                   |   |        |      |      |       |
|-------------------------------------|-----------------------------------|---|--------|------|------|-------|
| Symbol                              | Parameter                         | Test Conditions   | Rating |      |      | Units |
|                                     |                                   |   | Min.   | Typ. | Max. |       |
| V <sub>DSS</sub>                    | Drain to Source Breakdown Voltage | V <sub>GS</sub> =0V, I <sub>D</sub> =250μA                        | 100    | --   | --   | V     |
| ΔBV <sub>DSS</sub> /ΔT <sub>J</sub> | Bvdss Temperature Coefficient     | I <sub>D</sub> =250uA, Reference 25°C                             | --     | 0.1  | --   | V/°C  |
| I <sub>DSS</sub>                    | Drain to Source Leakage Current   | V <sub>DS</sub> =100V, V <sub>GS</sub> =0V, T <sub>a</sub> =25°C  | --     | --   | 1    | μA    |
|                                     |                                   | V <sub>DS</sub> =80V, V <sub>GS</sub> = 0V, T <sub>a</sub> =125°C | --     | --   | 250  |       |
| I <sub>GSS(F)</sub>                 | Gate to Source Forward Leakage    | V <sub>GS</sub> = +20V  | --     | --   | 1    | μA    |
| I <sub>GSS(R)</sub>                 | Gate to Source Reverse Leakage    | V <sub>GS</sub> = -20V  | --     | --   | -1   | μA    |

| ON Characteristics             |                               |  |        |      |      |       |
|--------------------------------|-------------------------------|--|--------|------|------|-------|
| Symbol                         | Parameter                     | Test Conditions  | Rating |      |      | Units |
|                                |                               |  | Min.   | Typ. | Max. |       |
| R <sub>DS(ON)</sub>            | Drain-to-Source On-Resistance | V <sub>GS</sub> =10V, I <sub>D</sub> =10A                  | --     | 20   | 30   | mΩ    |
| V <sub>GS(TH)</sub>            | Gate Threshold Voltage        | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA | 1.0    | --   | 3.0  | V     |
| Pulse width tp ≤ 380μs, δ ≤ 2% |                               |  |        |      |      |       |

| Dynamic Characteristics |                              |   |        |      |      |       |
|-------------------------|------------------------------|---|--------|------|------|-------|
| Symbol                  | Parameter                    | Test Conditions                                       | Rating |      |      | Units |
|                         |                              |   | Min.   | Typ. | Max. |       |
| g <sub>fs</sub>         | Forward Transconductance     | V <sub>DS</sub> =5V, I <sub>D</sub> =10.0A            | 8.0    | --   | --   | S     |
| C <sub>iss</sub>        | Input Capacitance            | V <sub>GS</sub> =0V, V <sub>DS</sub> =50V<br>f=1.0MHz | --     | 2000 | --   | pF    |
| C <sub>oss</sub>        | Output Capacitance           |   | --     | 300  | --   |       |
| C <sub>rss</sub>        | Reverse Transfer Capacitance |   | --     | 250  | --   |       |

| Resistive Switching Characteristics |                                   |   |        |      |      |       |
|-------------------------------------|-----------------------------------|---|--------|------|------|-------|
| Symbol                              | Parameter                         | Test Conditions   | Rating |      |      | Units |
|                                     |                                   |   | Min.   | Typ. | Max. |       |
| t <sub>d(ON)</sub>                  | Turn-on Delay Time                | I <sub>D</sub> =15A, V <sub>DD</sub> =50V<br>V <sub>GS</sub> =10V, R <sub>G</sub> =3.0Ω | --     | 10   | --   | ns    |
| t <sub>r</sub>                      | Rise Time                         |   | --     | 10   | --   |       |
| t <sub>d(OFF)</sub>                 | Turn-Off Delay Time               |   | --     | 38   | --   |       |
| t <sub>f</sub>                      | Fall Time                         |   | --     | 14   | --   |       |
| Q <sub>g</sub>                      | Total Gate Charge                 | I <sub>D</sub> =15A, V <sub>DD</sub> =50V<br>V <sub>GS</sub> =10V                       | --     | 45   | --   | nC    |
| Q <sub>gs</sub>                     | Gate to Source Charge             |   | --     | 12   | --   |       |
| Q <sub>gd</sub>                     | Gate to Drain ( "Miller" ) Charge |   | --     | 18   | --   |       |

## GL Silicon N-Channel Power MOSFET

### Source-Drain Diode Characteristics

| Symbol   | Parameter                              | Test Conditions              | Rating |      |      | Units |
|----------|--|------------------------------|--------|------|------|-------|
|          |  |                              | Min.   | Typ. | Max. |       |
| $I_S$    | Continuous Source Current (Body Diode) |                              | --     | --   | 30   | A     |
| $I_{SM}$ | Maximum Pulsed Current (Body Diode)    |                              | --     | --   | 120  | A     |
| $V_{SD}$ | Diode Forward Voltage                  | $I_S=30A, V_{GS}=0V$         | --     | --   | 1.5  | V     |
| $t_{rr}$ | Reverse Recovery Time                  | $I_S=30A, T_j = 25^\circ C$  | --     | 66   | --   | ns    |
| $Q_{rr}$ | Reverse Recovery Charge                | $dI_F/dt=100A/us, V_{GS}=0V$ | --     | 130  | --   | nC    |

Pulse width  $t_p \leq 380\mu s, \delta \leq 2\%$

| Symbol          | Parameter        | Typ. | Units        |
|-----------------|------------------|------|--------------|
| $R_{\theta JC}$ | Junction-to-Case | 1.8  | $^\circ C/W$ |

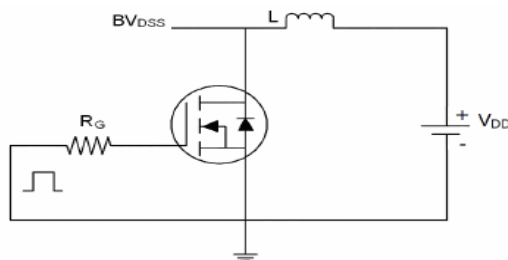
<sup>a1</sup> : Repetitive rating; pulse width limited by maximum junction temperature

<sup>a2</sup> : EAS condition :  $T_j=25^\circ C, V_{DD}=40V, V_G=10V, L=0.5mH, R_g=25\Omega$

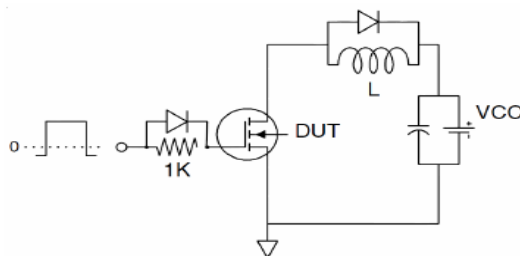
<sup>a3</sup> :  $I_{SD} = 30A, di/dt \leq 100A/us, V_{DD} \leq BV_{DS}, \text{Start } T_j=25^\circ C$

### Test Circuit

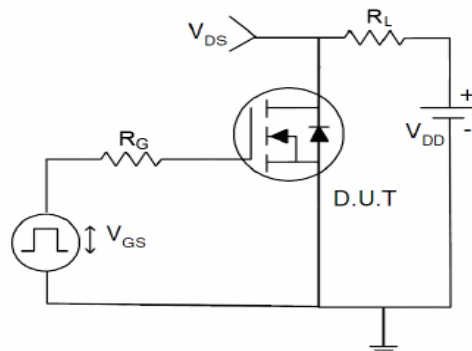
#### 1) EAS test Circuit



#### 2) Gate charge test Circuit



#### 3) Switch Time Test Circuit





## GL Silicon N-Channel Power MOSFET

### Typical Electrical and Thermal Characteristics (Curves)

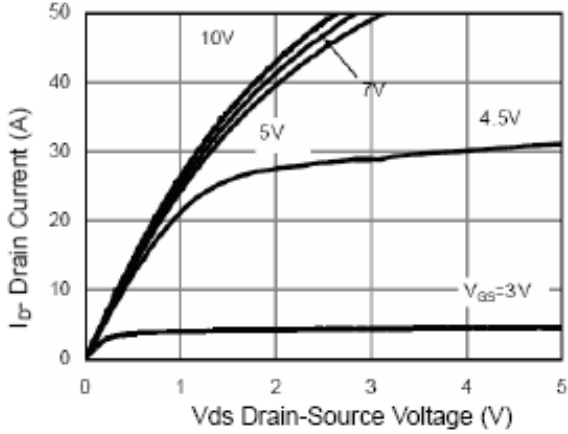


Figure 1 Output Characteristics

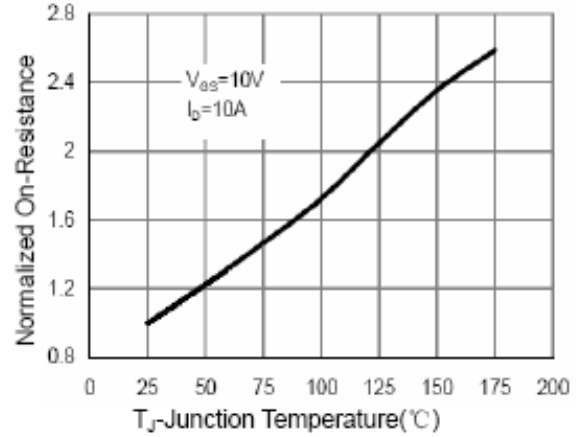


Figure 4  $R_{dson}$ -Junction Temperature

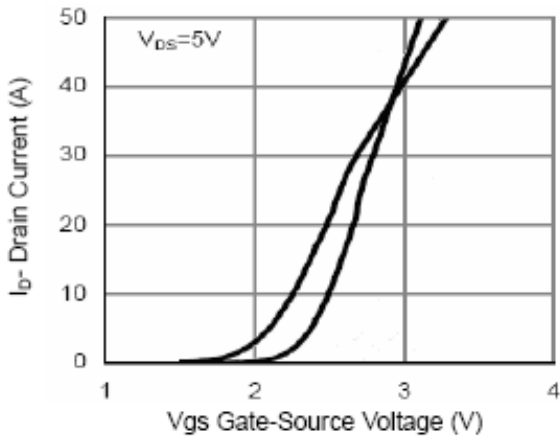


Figure 2 Transfer Characteristics

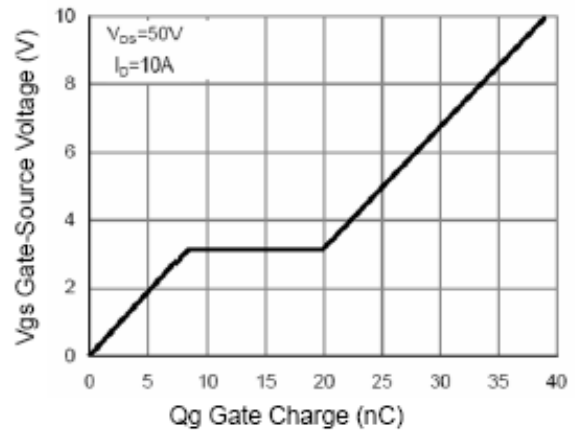


Figure 5 Gate Charge

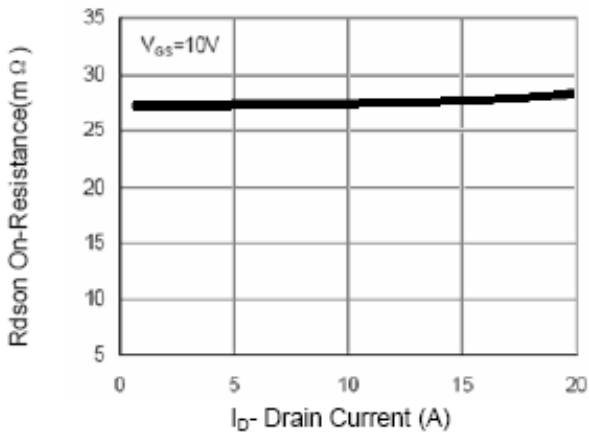


Figure 3  $R_{dson}$ - Drain Current

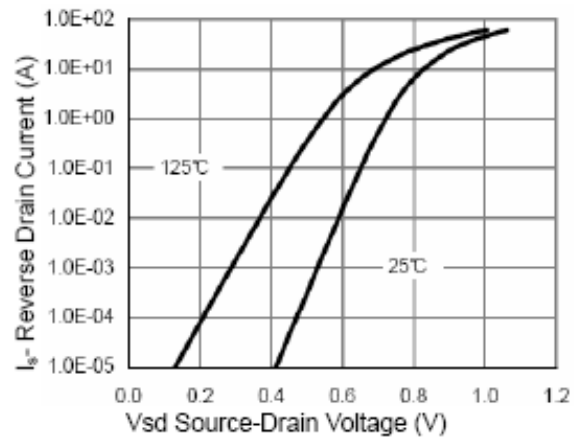


Figure 6 Source- Drain Diode Forward



# CS540A4

无锡光磊电子科技有限公司

## GL Silicon N-Channel Power MOSFET

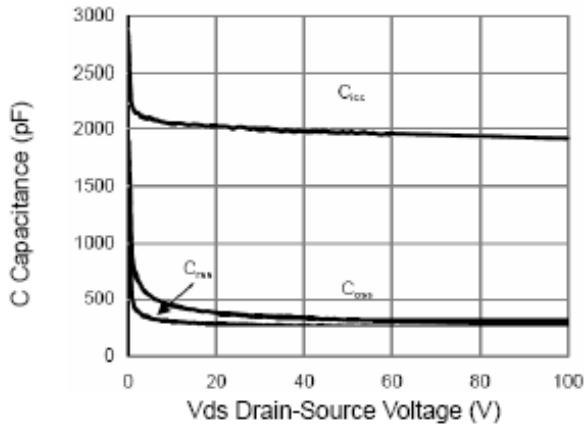


Figure 7 Capacitance vs Vds

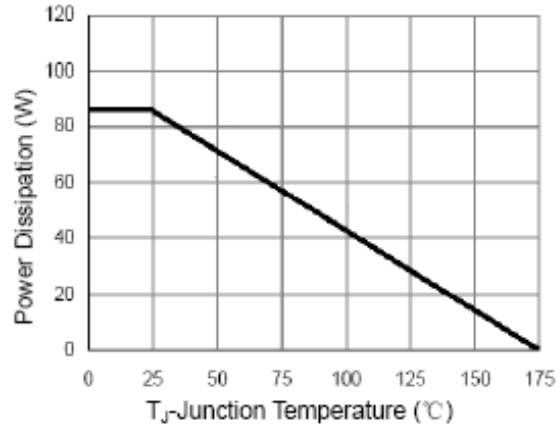


Figure 9 Power De-rating

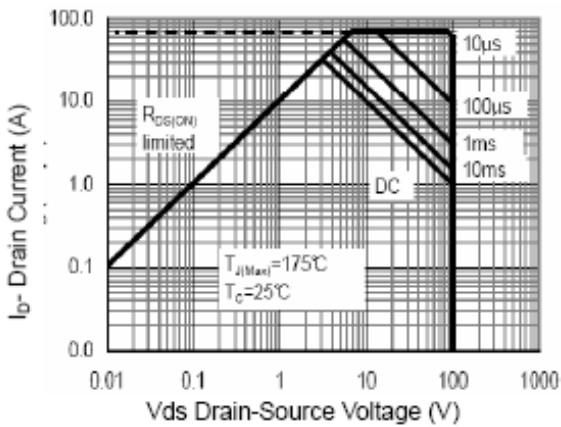


Figure 8 Safe Operation Area

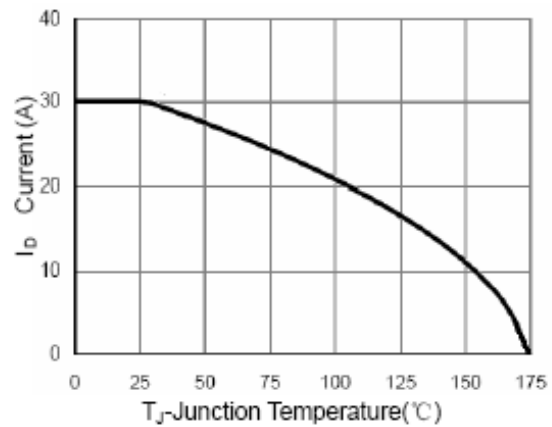


Figure 10 ID Current-Junction Temperature

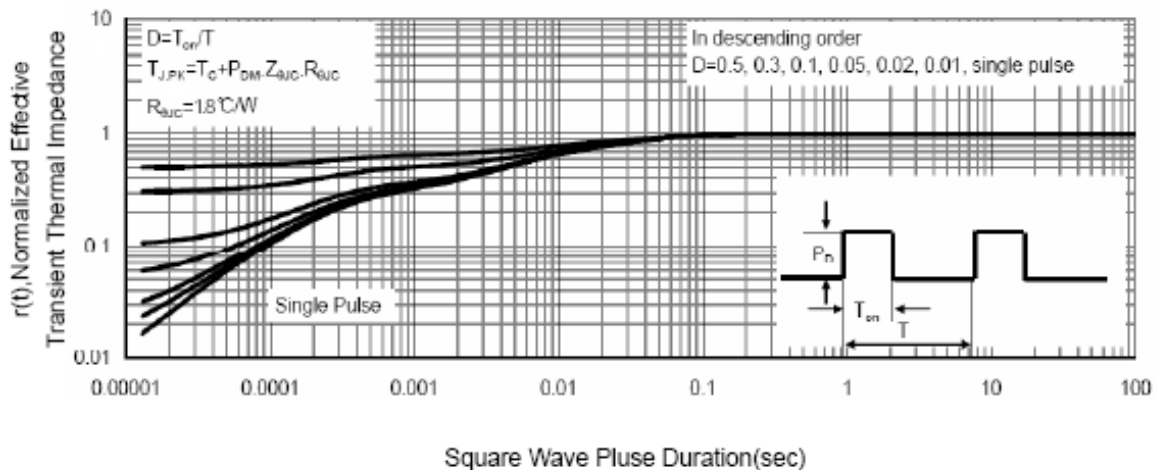


Figure 11 Normalized Maximum Transient Thermal Impedance

TEL:0755-23068119